

HAF2011(L), HAF2011(S)

Silicon N Channel MOS FET Series
Power Switching

REJ03G1138-0500

Rev.5.00

Aug 21, 2007

Description

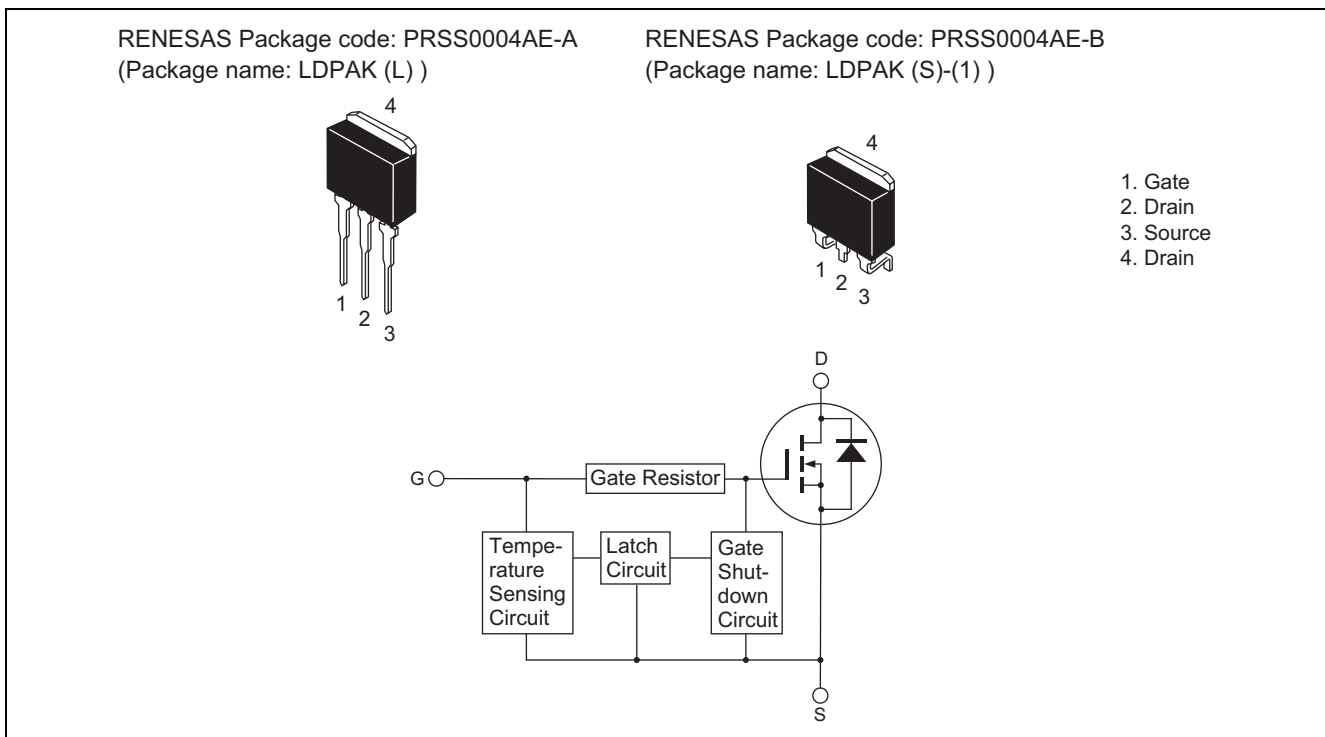
This FET has the over temperature shut-down capability sensing to the junction temperature.

This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc.

Features

- Logic level operation (4 to 6 V Gate drive)
- High endurance capability against to the short circuit
- Built-in the over temperature shut-down circuit
- Latch type shut-down operation (Need 0 voltage recovery)

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Drain to source voltage	V _{DS}	60	V
Gate to source voltage	V _{GS}	16	V
	V _{GSS}	-2.5	V
Drain current	I _D	40	A
Drain peak current	I _{D (pulse)} ^{Note 1}	80	A
Body-drain diode reverse drain current	I _{DR}	40	A
Channel dissipation	P _{ch} ^{Note 2}	50	W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Notes: 1. PW ≤ 10 μs, duty cycle ≤ 1%

2. Value at Tc = 25°C

Typical Operation Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage	V _{IH}	3.5	—	—	V	
	V _{IL}	—	—	1.2	V	
Input current (Gate non shut down)	I _{IH1}	—	—	100	μA	V _i = 8 V, V _{DS} = 0
	I _{IH2}	—	—	50	μA	V _i = 3.5 V, V _{DS} = 0
	I _{IL}	—	—	1	μA	V _i = 1.2 V, V _{DS} = 0
Input current (Gate shut down)	I _{IH (sd) 1}	—	0.8	—	mA	V _i = 8 V, V _{DS} = 0
	I _{IH (sd) 2}	—	0.35	—	mA	V _i = 3.5 V, V _{DS} = 0
Shut down temperature	T _{sd}	—	175	—	°C	Channel temperature
Gate operation voltage	V _{OP}	3.5	—	12	V	

Electrical Characteristics

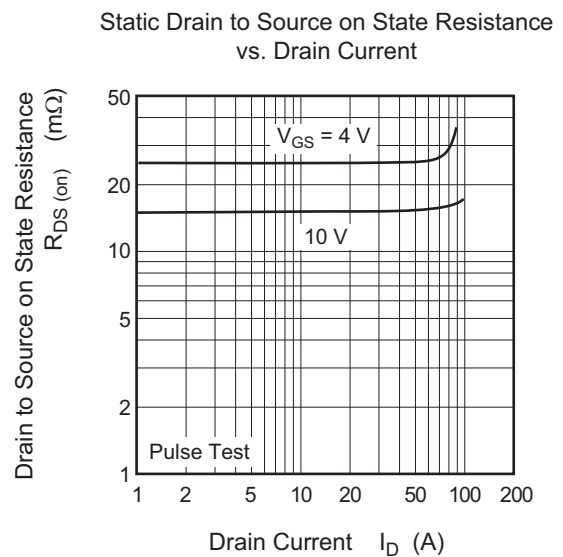
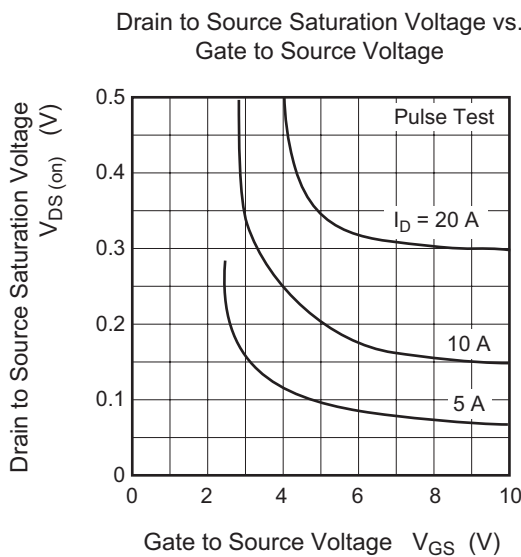
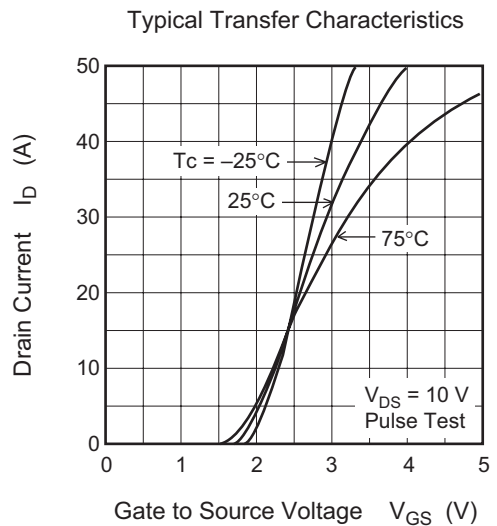
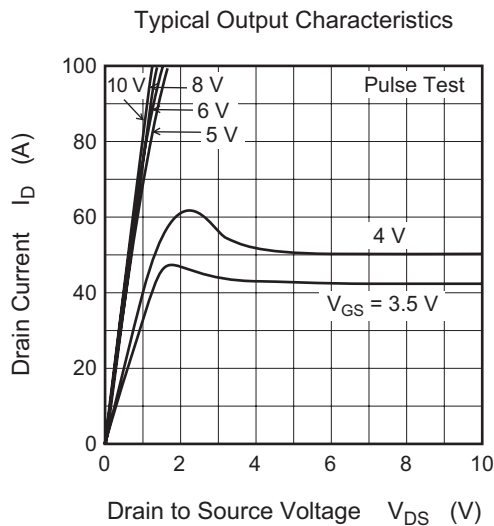
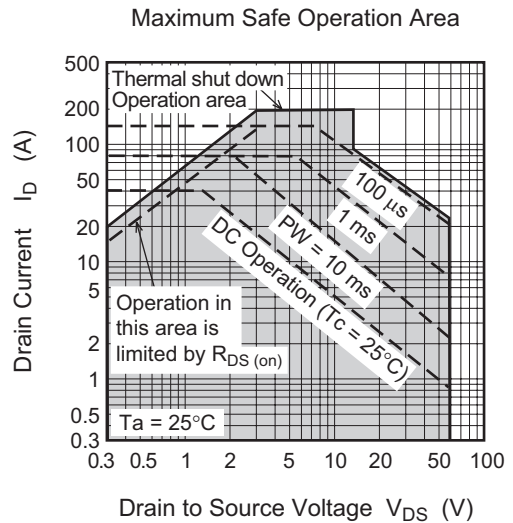
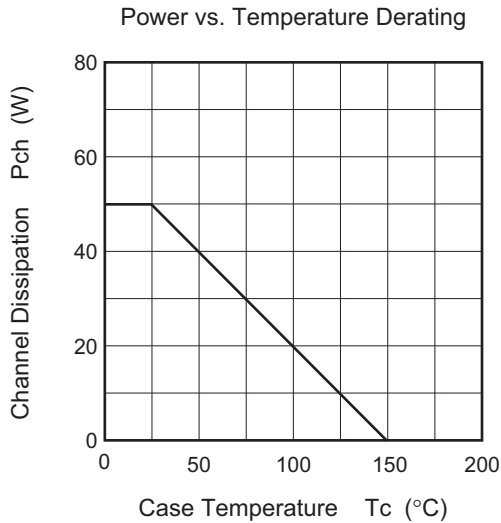
(Ta = 25°C)

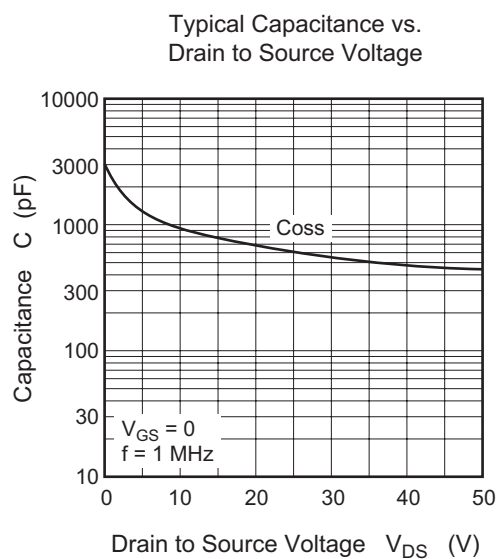
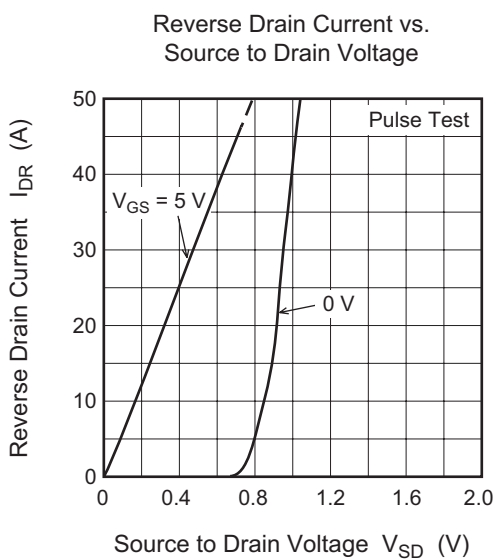
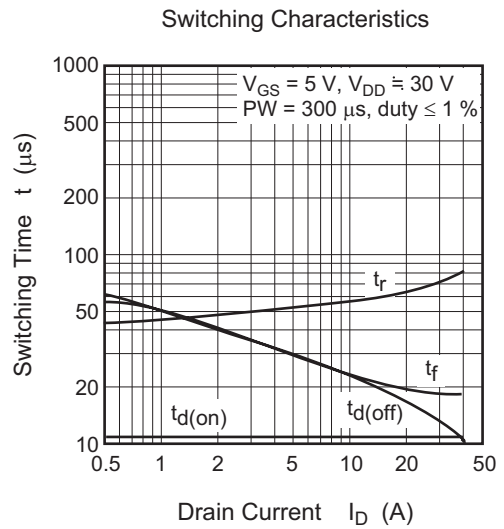
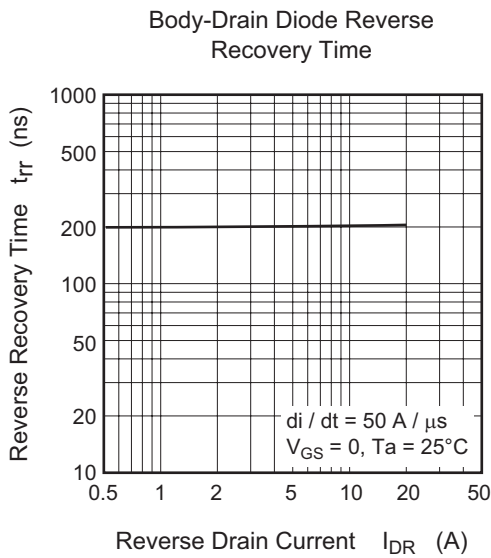
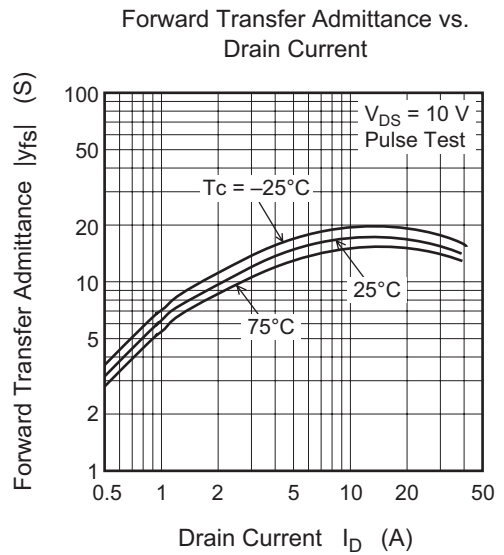
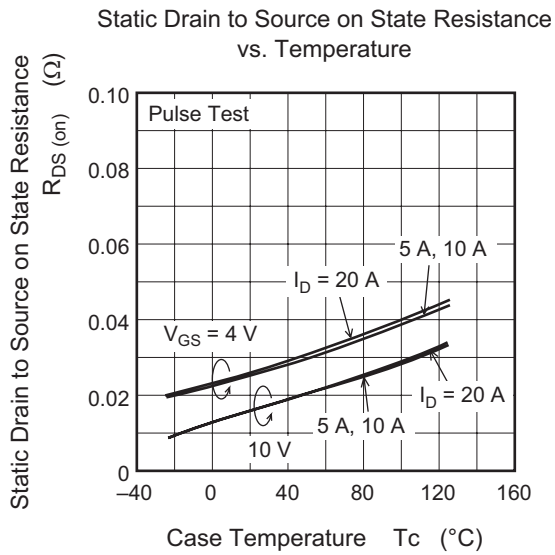
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain current	I_{D1}	15	—	—	A	$V_{GS} = 3.5 \text{ V}, V_{DS} = 2 \text{ V}$
	I_{D2}	—	—	10	mA	$V_{GS} = 1.2 \text{ V}, V_{DS} = 2 \text{ V}$
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	16	—	—	V	$I_G = 300 \mu\text{A}, V_{DS} = 0$
	$V_{(BR)GSS}$	-2.5	—	—	V	$I_G = -100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS1}	—	—	100	μA	$V_{GS} = 8 \text{ V}, V_{DS} = 0$
	I_{GSS2}	—	—	50	μA	$V_{GS} = 3.5 \text{ V}, V_{DS} = 0$
	I_{GSS3}	—	—	1	μA	$V_{GS} = 1.2 \text{ V}, V_{DS} = 0$
	I_{GSS4}	—	—	-100	μA	$V_{GS} = -2.4 \text{ V}, V_{DS} = 0$
Input current (shut down)	$I_{GS(op)1}$	—	0.8	—	mA	$V_{GS} = 8 \text{ V}, V_{DS} = 0$
	$I_{GS(op)2}$	—	0.35	—	mA	$V_{GS} = 3.5 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	10	μA	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.25	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	25	33	m Ω	$I_D = 20 \text{ A}, V_{GS} = 4 \text{ V}$ ^{Note 3}
	$R_{DS(on)}$	—	15	20	m Ω	$I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}$ ^{Note 3}
Forward transfer admittance	$ y_{fs} $	8	16	—	S	$I_D = 20 \text{ A}, V_{DS} = 10 \text{ V}$ ^{Note 3}
Output capacitance	C_{oss}	—	940	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0$ $f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	10.7	—	μs	$I_D = 20 \text{ A}$ $V_{GS} = 5 \text{ V}$ $R_L = 1.5 \Omega$
Rise time	t_r	—	66	—	μs	
Turn-off delay time	$t_{d(off)}$	—	15.5	—	μs	
Fall time	t_f	—	19	—	μs	
Body-drain diode forward voltage	V_{DF}	—	1	—	V	$I_F = 40 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t_{rr}	—	200	—	ns	$I_F = 40 \text{ A}, V_{GS} = 0$ $di_F/dt = 50 \text{ A}/\mu\text{s}$
Over load shut down operation time ^{Note4}	t_{os1}	—	1	—	ms	$V_{GS} = 5 \text{ V}, V_{DD} = 16 \text{ V}$

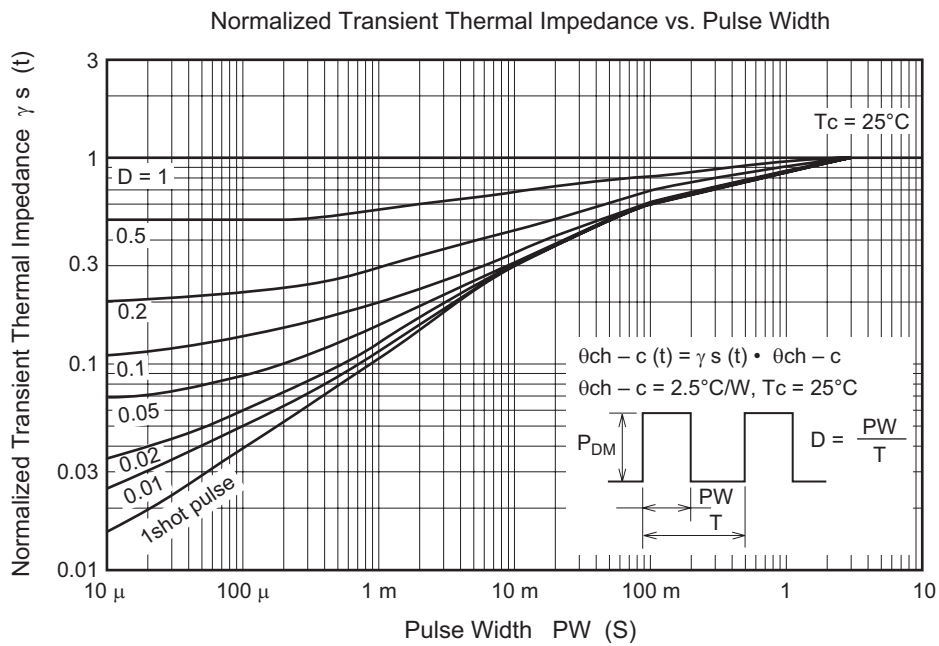
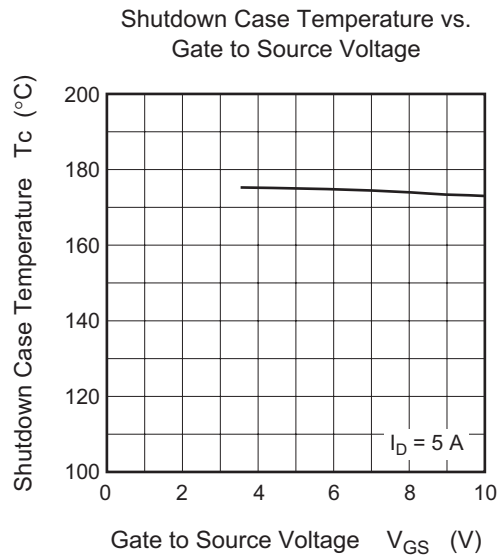
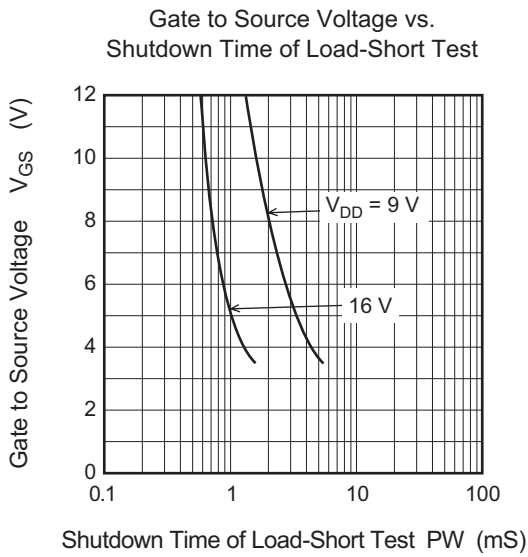
Notes: 3. Pulse test

4. Including the junction temperature rise of the over loaded condition.

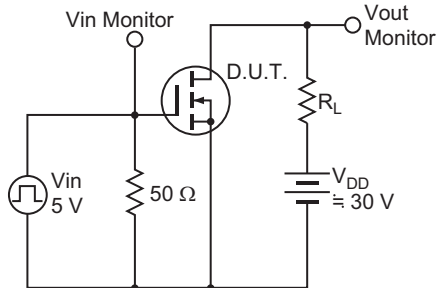
Main Characteristics



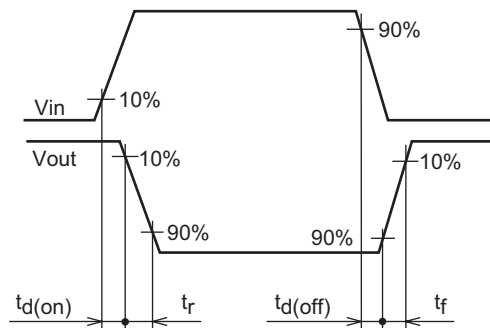




Switching Time Test Circuit



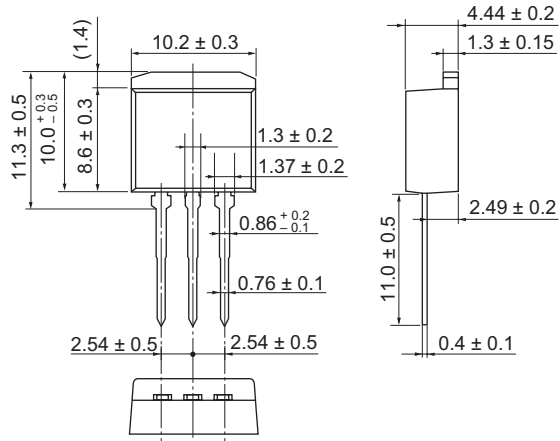
Waveform



Package Dimensions

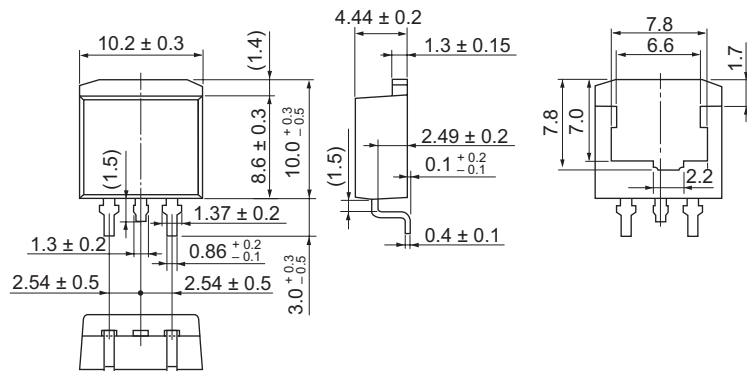
Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
LDBPAK(L)	—	PRSS0004AE-A	LDBPAK(L) / LDBPAK(L)V	1.40g

Unit: mm



Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
LDBPAK(S)-(1)	SC-83	PRSS0004AE-B	LDBPAK(S)-(1) / LDBPAK(S)-(1)V	1.30g

Unit: mm



Ordering Information

Part No.	Quantity	Shipping Container
HAF2011-90L	Max: 50 pcs/sack	Sack
HAF2011-90S	Max: 50 pcs/sack	Sack
HAF2011-90STL	1000 pcs/Reel	Embossed tape
HAF2011-90STR	1000 pcs/Reel	Embossed tape

Notes:

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